# Silicon P Channel Power MOS FET High Speed Power Switching

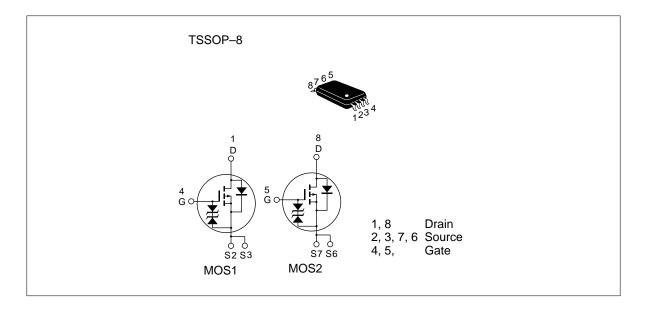
# **HITACHI**

ADE-208-527 B (Z) Target Specification 3rd. Edition June 1997

#### **Features**

- Low on-resistance
- Capable of 2.5 V gate drive
- Low drive current
- High density mounting

### **Outline**



## **Absolute Maximum Ratings** $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V <sub>DSS</sub>	<b>-12</b>	V	
Gate to source voltage	$V_{GSS}$	±10	V	
Drain current	I <sub>D</sub>	-3	Α	
Drain peak current	I Note1	-24	А	
Body-drain diode reverse drain current	I <sub>DR</sub>	-3	Α	
Channel dissipation	Pch Note2	1	W	
Channel dissipation	Pch Note3	1.5	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Note: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

- 2. 1 Drive operation : When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW $\leq$  10s
- 3. 2 Drive operation : When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW $\leq$  10s

## **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

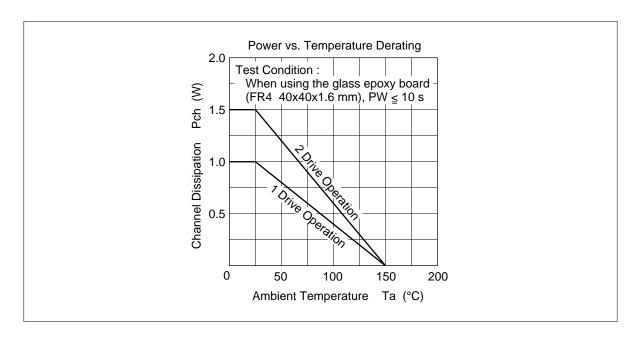
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-12	_	_	V	$I_D = -10 \text{mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±10			V	$I_{G} = \pm 100 \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_		±10	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0$
Zero gate voltege drain current	I <sub>DSS</sub>	_		-1	μΑ	$V_{DS} = -12 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-0.5		-1.5	V	$V_{DS} = -10V, I_{D} = -1mA$
Static drain to source on state	R <sub>DS(on)</sub>	_	(0.085)	(0.1)	Ω	$I_{\rm D} = -2A, V_{\rm GS} = -4V^{\rm Note4}$
resistance	$R_{\rm DS(on)}$		(0.12)	(0.18)	Ω	$I_D = -2A, V_{GS} = -2.5V^{Note4}$
Forward transfer admittance	y <sub>fs</sub>	(TBD)	(TBD)	_	S	$I_{\rm D} = -2A, V_{\rm DS} = -10V^{\rm Note4}$
Input capacitance	Ciss	_	(TBD)	_	pF	$V_{DS} = -10V$
Output capacitance	Coss		(TBD)	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		(TBD)	_	pF	f = 1MHz
Turn-on delay time	t <sub>d(on)</sub>	_	(TBD)	_	ns	$V_{GS} = -4V, I_{D} = -2A$
Rise time	t <sub>r</sub>	_	(TBD)	_	ns	$V_{DD} \cong -10V$
Turn-off delay time	t <sub>d(off)</sub>	_	(TBD)	_	ns	_
Fall time	t <sub>f</sub>	_	(TBD)	_	ns	

## **Electrical Characteristics** (Ta = 25°C) (cont)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Body-drain diode forward voltage	$V_{DF}$	_	(TBD)	(TBD)	V	$IF = -3A, V_{GS} = 0^{Note4}$
Body-drain diode reverse recovery time	t <sub>rr</sub>		(TBD)	_	ns	IF = $-3A$ , $V_{GS} = 0$ diF/ dt =20A/ $\mu$ s

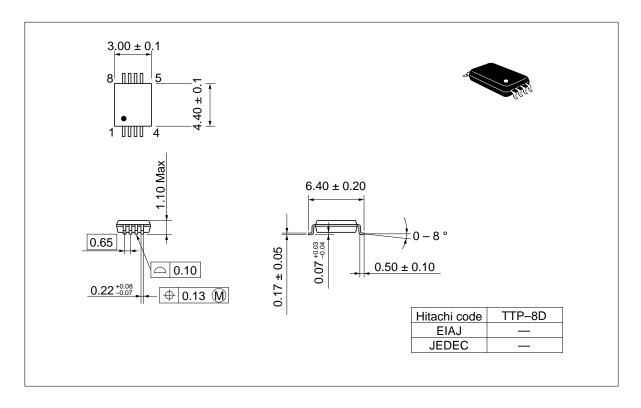
Note: 4. Pulse test

## **Main Characteristics**



# **Package Dimensions**

Unit: mm



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